

60A, 30V, 0.027 Ohm, P-Channel Power MOSFETs

These P-Channel power MOSFETs are manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI integrated circuits gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49045.

Ordering Information

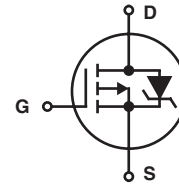
| PART NUMBER | PACKAGE | BRAND |
|-------------|----------|----------|
| RFG60P03 | TO-247 | RFG60P03 |
| RFP60P03 | TO-220AB | RFP60P03 |
| RF1S60P03SM | TO-263AB | F1S60P03 |

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-263AB variant in tape and reel, i.e. RF1S60P03SM9A.

Features

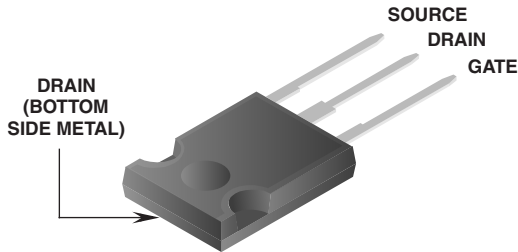
- 60A, 30V
- $r_{DS(ON)} = 0.027\Omega$
- Temperature Compensating PSPICE® Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol

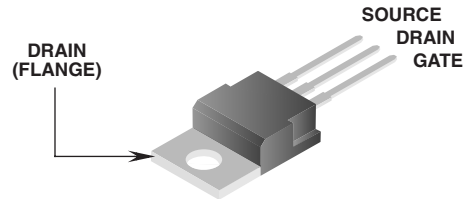


Packaging

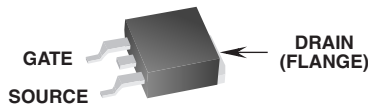
JEDEC STYLE TO-247



JEDEC TO-220AB



JEDEC TO-263AB



RFG60P03, RFP60P03, RF1S60P03SM

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

| | RFG60P03, RFP60P03, RFS60P03SM | UNITS |
|--|--------------------------------------|---------------------|
| Drain to Source Voltage (Note 1) | V_{DSS} -30 | V |
| Drain to Gate Voltage, ($R_{GS} = 20k\Omega$) (Note 1) | V_{DGR} -30 | V |
| Gate to Source Voltage | V_{GS} ± 20 | V |
| Continuous Drain Current (Figure 2) | I_D 60 | A |
| Pulsed Drain Current (Note 3) | I_{DM} Refer to Peak Current Curve | |
| Single Pulse Avalanche Rating | E_{AS} Figure 6 | |
| Maximum Power Dissipation (Figure 1) | P_D 176 | W |
| Derate Above 25°C | 1.17 | W/ $^\circ\text{C}$ |
| Operating and Storage Temperature | T_J, T_{STG} -55 to 175 | $^\circ\text{C}$ |
| Maximum Temperature for Soldering | | |
| Leads at 0.063in (1.6mm) from Case for 10s | T_L 300 | $^\circ\text{C}$ |
| Package Body for 10s, See Techbrief 334 | T_{pkg} 260 | $^\circ\text{C}$ |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- $T_J = 25^\circ\text{C}$ to 150°C .

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|-------------------|---|-----|------|-----------|--------------------|
| Drain to Source Breakdown Voltage | BV_{DSS} | $I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$ (Figure 11) | -30 | - | - | V |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ (Figure 10) | -2 | - | -4 | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = \text{Rated } BV_{DSS}, V_{GS} = 0\text{V}$ | - | - | -1 | μA |
| | | $V_{DS} = 0.8 \times \text{Rated } BV_{DSS}, T_C = 150^\circ\text{C}$ | - | - | -50 | μA |
| Gate to Source Leakage Current | I_{GSS} | $V_{GS} = \pm 20\text{V}$ | - | - | ± 100 | nA |
| Drain to Source On Resistance (Note 2) | $r_{DS(ON)}$ | $I_D = 60\text{A}, V_{GS} = 10\text{V}$ | - | - | 0.027 | Ω |
| Turn-On Time | t_{ON} | $V_{DD} = 15\text{V}, I_D \approx 60\text{A}, R_L = 0.25\Omega,$ $V_{GS} = -10\text{V}, R_G = 2.5\Omega,$ (Figure 13) | - | - | 140 | ns |
| Turn-On Delay Time | $t_{d(ON)}$ | | - | 20 | - | ns |
| Rise Time | t_r | | - | 75 | - | ns |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | - | 35 | - | ns |
| Fall Time | t_f | | - | 40 | - | ns |
| Turn-Off Time | t_{OFF} | | - | - | 115 | ns |
| Total Gate Charge | $Q_g(\text{TOT})$ | $V_{GS} = 0$ to -20V | - | 190 | 230 | nC |
| Gate Charge at 10V | $Q_g(-10)$ | $V_{GS} = 0$ to -10V | | | | |
| Threshold Gate Charge | $Q_g(\text{TH})$ | $V_{GS} = 0$ to -2V | | | | |
| Input Capacitance | C_{ISS} | $V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ (Figure 12) | - | 3000 | - | pF |
| Output Capacitance | C_{OSS} | | - | 1500 | - | pF |
| Reverse Transfer Capacitance | C_{RSS} | | - | 525 | - | pF |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | (Figure 3) | - | - | 0.85 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | TO-220AB, TO- 263AB | - | - | 62 | $^\circ\text{C/W}$ |
| | | TO-247 | - | - | 30 | $^\circ\text{C/W}$ |

Source to Drain Diode Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|--|----------|--|-----|-----|-------|-------|
| Source to Drain Diode Voltage (Note 2) | V_{SD} | $I_{SD} = -60\text{A}$ | - | - | -1.75 | V |
| Diode Reverse Recovery Time | t_{rr} | $I_{SD} = -60\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$ | - | - | 200 | ns |

NOTE:

- Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Repetitive rating: pulse width limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3)

Typical Performance Curves Unless Otherwise Specified

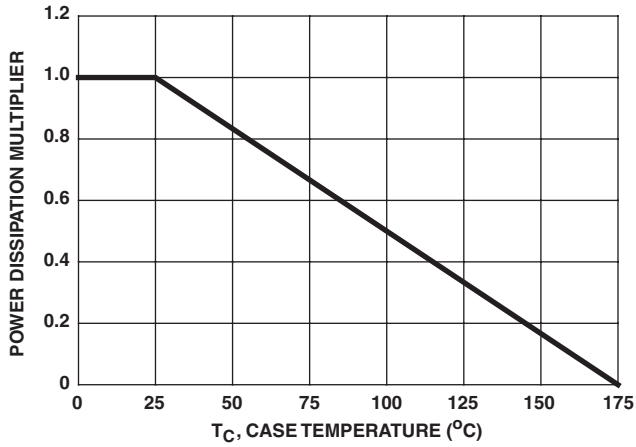


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

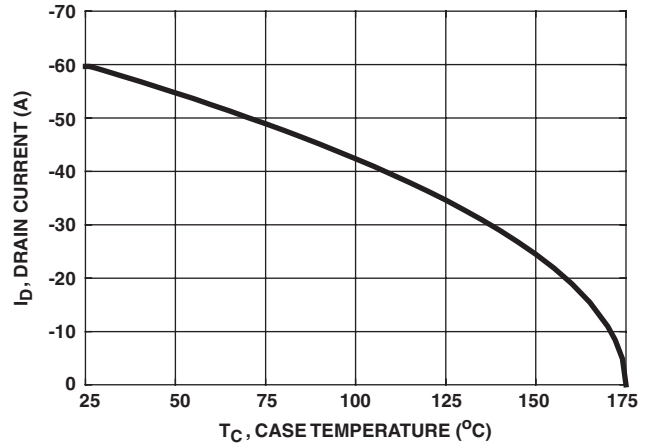


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

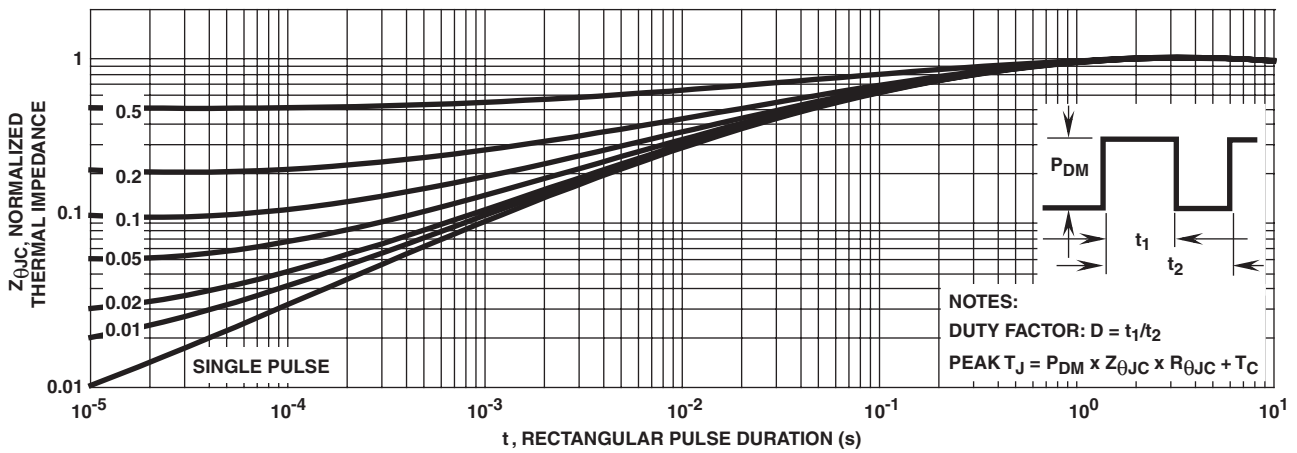


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

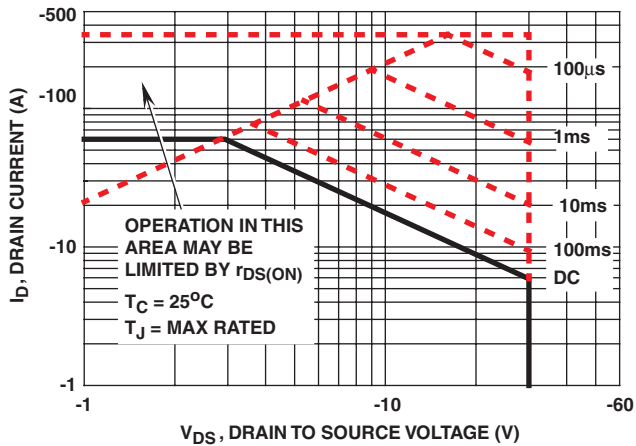


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

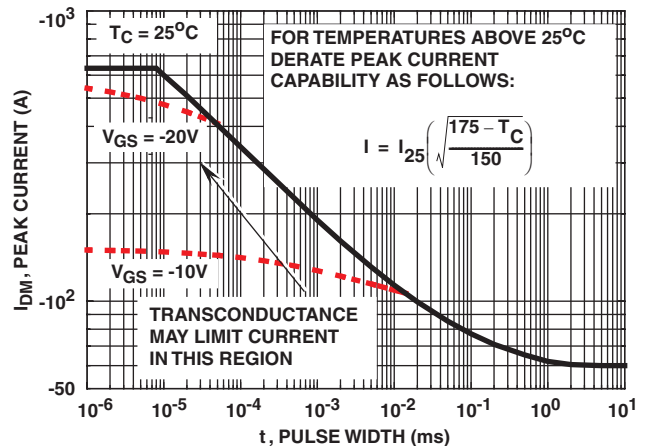
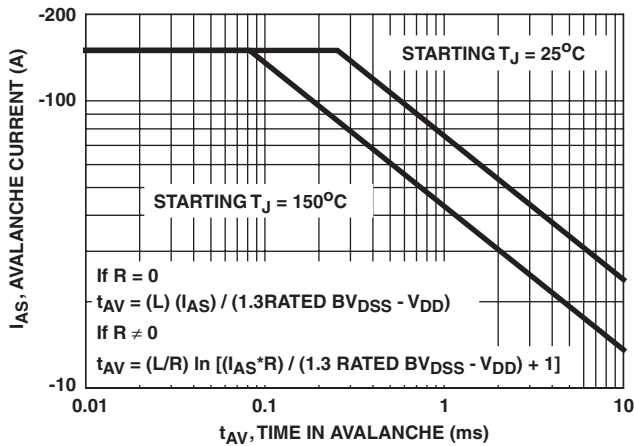


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves Unless Otherwise Specified (Continued)



NOTE: Refer to Fairchild Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

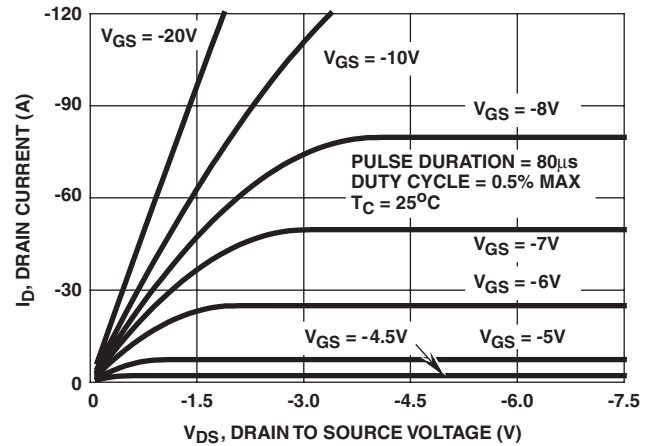


FIGURE 7. SATURATION CHARACTERISTICS

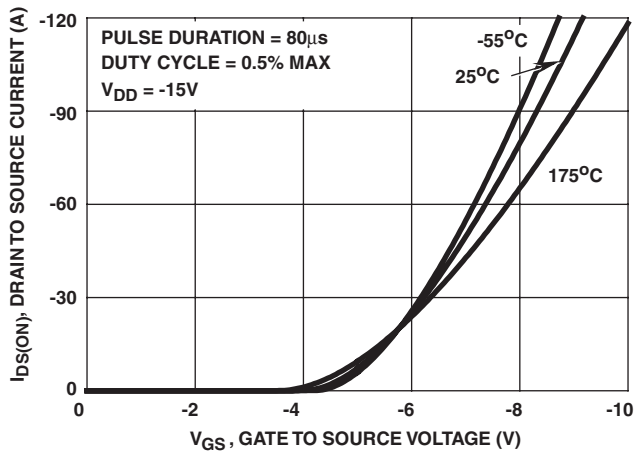


FIGURE 8. TRANSFER CHARACTERISTICS

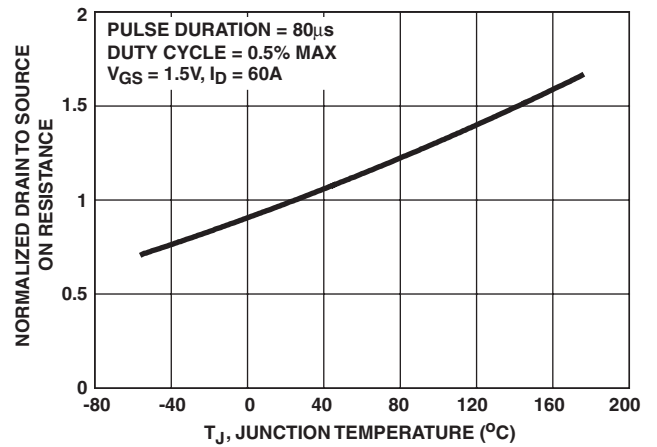


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

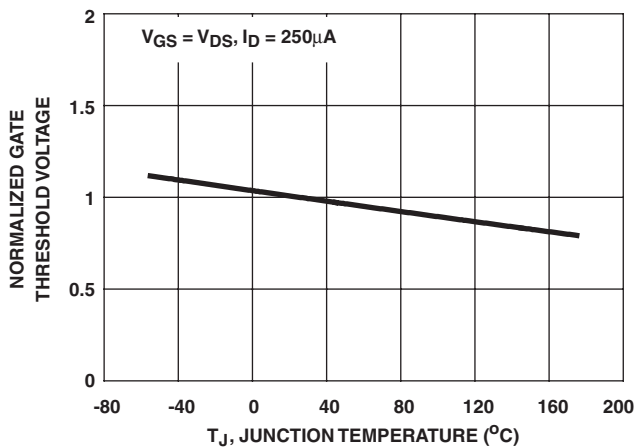


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

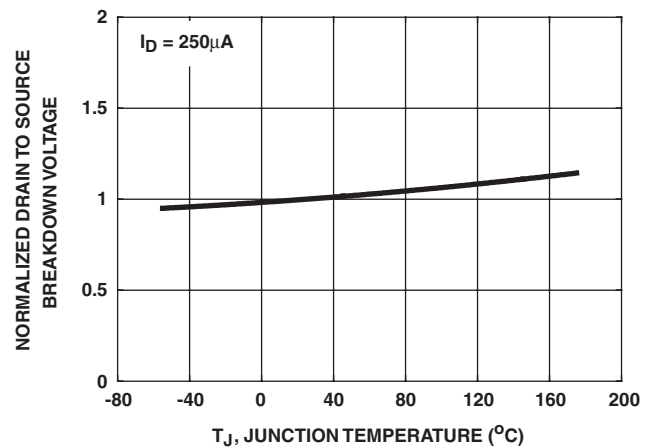


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

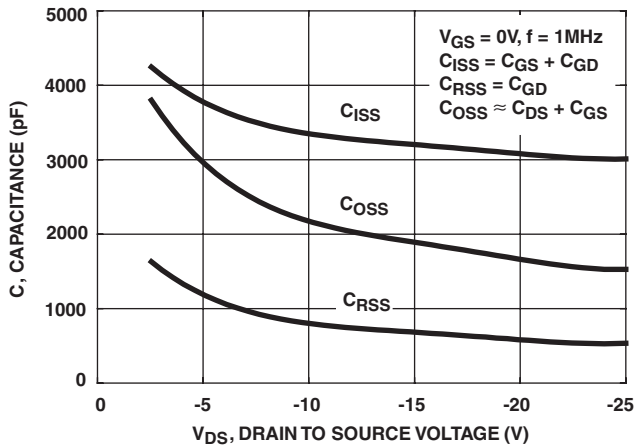
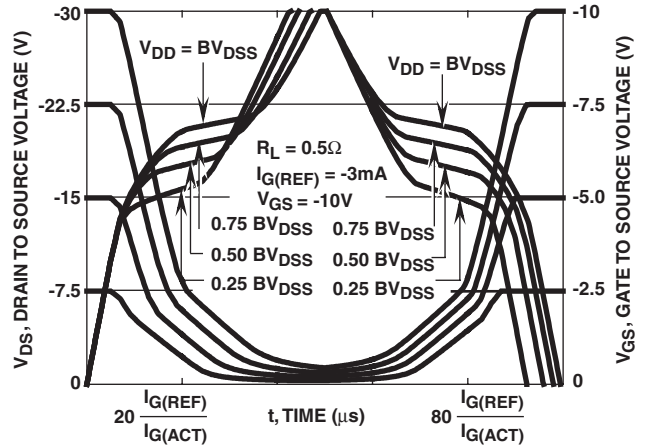


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

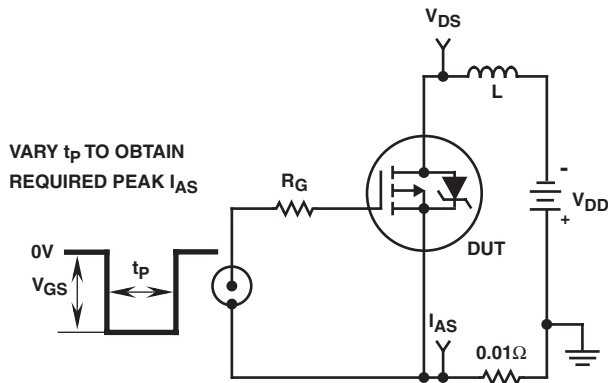


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

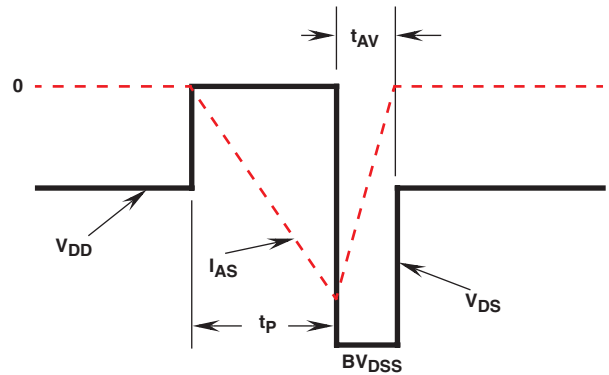


FIGURE 15. UNCLAMPED ENERGY WAVEFORM

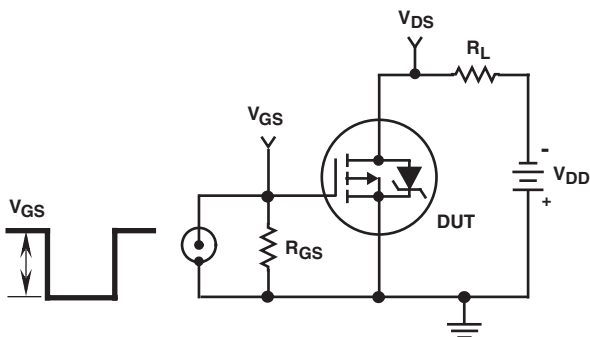


FIGURE 16. SWITCHING TIME TEST CIRCUIT

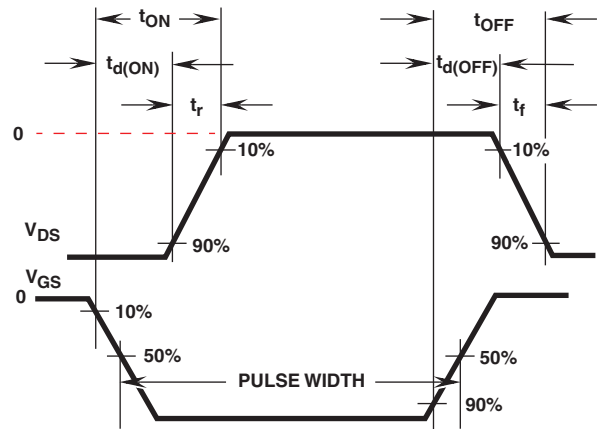


FIGURE 17. RESISTIVE SWITCHING WAVEFORMS

Test Circuits and Waveforms (Continued)

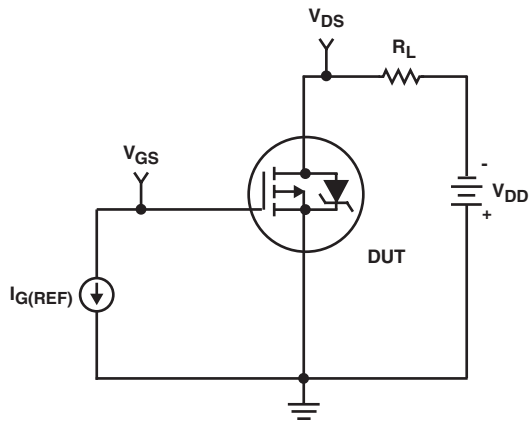


FIGURE 18. GATE CHARGE TEST CIRCUIT

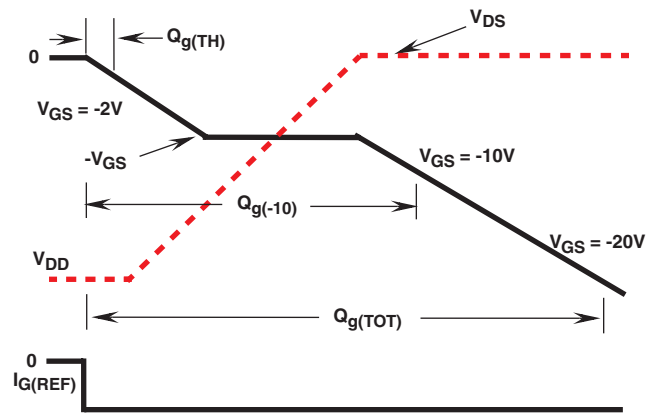


FIGURE 19. GATE CHARGE WAVEFORMS

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